

TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

features

- Dual 8-Bit Voltage Output DAC
- Programmable Internal Reference
- Programmable Settling Time
 - 3 μ s in Fast Mode
 - 10 μ s in Slow Mode
- Compatible With TMS320 and SPI™ Serial Ports
- Differential Nonlinearity <0.2 LSB Max
- Monotonic Over Temperature

applications

- Digital Servo Control Loops
- Digital Offset and Gain Adjustment
- Industrial Process Control
- Machine and Motion Control Devices
- Mass Storage Devices

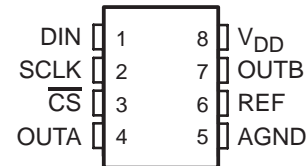
description

The TLV5625 is a dual 8-bit voltage output DAC with a flexible 3-wire serial interface. The serial interface is compatible with TMS320, SPI™, QSPI™, and Microwire™ serial ports. It is programmed with a 16-bit serial string containing 4 control and 8 data bits.

The resistor string output voltage is buffered by an x2 gain rail-to-rail output buffer. The buffer features a Class-AB output stage to improve stability and reduce settling time. The programmable settling time of the DAC allows the designer to optimize speed versus power dissipation.

Implemented with a CMOS process, the device is designed for single supply operation from 2.7 V to 5.5 V. It is available in an 8-pin SOIC package in standard commercial and industrial temperature ranges.

D PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T _A	PACKAGE
	SOIC (D)
0°C to 70°C	TLV5625CD
–40°C to 85°C	TLV5625ID



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SPI and QSPI are trademarks of Motorola, Inc.
Microwire is a trademark of National Semiconductor Corporation.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

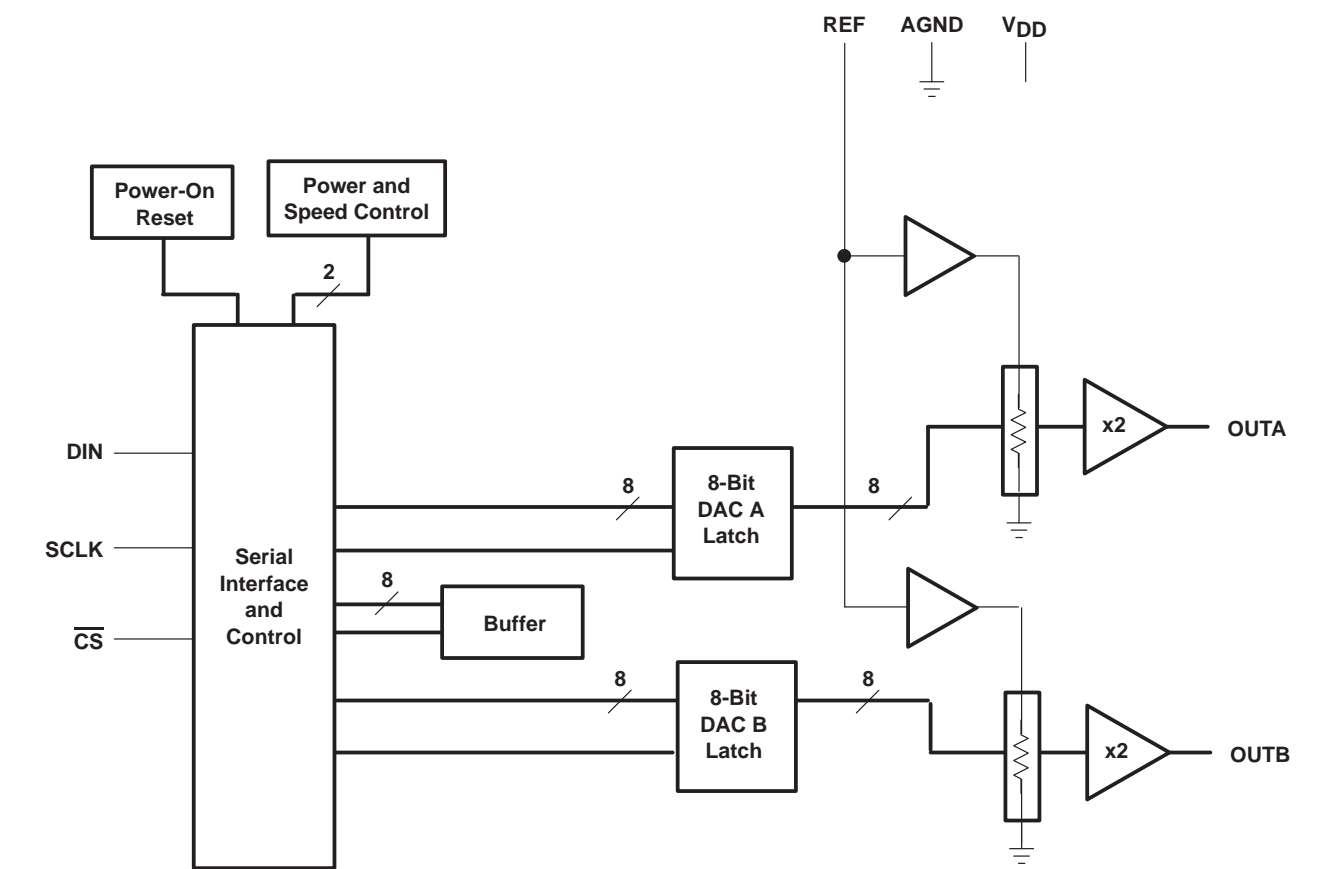
Copyright © 2002, Texas Instruments Incorporated

TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O/P	DESCRIPTION
AGND	5	P	Ground
$\overline{\text{CS}}$	3	I	Chip select. Digital input active low, used to enable/disable inputs.
DIN	1	I	Digital serial data input
OUTA	4	O	DAC A analog voltage output
OUTB	7	O	DAC B analog voltage output
REF	6	I	Analog reference voltage input
SCLK	2	I	Digital serial clock input
VDD	8	P	Positive power supply

TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage (V_{DD} to AGND)	7 V
Reference input voltage range	– 0.3 V to $V_{DD} + 0.3$ V
Digital input voltage range	– 0.3 V to $V_{DD} + 0.3$ V
Operating free-air temperature range, T_A : TLV5625C	0°C to 70°C
TLV5625I	–40°C to 85°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	$V_{DD} = 5$ V	4.5	5	5.5	V
	$V_{DD} = 3$ V	2.7	3	3.3	
Power on reset, POR		0.55		2	V
High-level digital input voltage, V_{IH}	$V_{DD} = 2.7$ V	2			V
	$V_{DD} = 5.5$ V	2.4			
Low-level digital input voltage, V_{IL}	$V_{DD} = 2.7$ V			0.6	V
	$V_{DD} = 5.5$ V			1	
Reference voltage, V_{ref} to REF terminal	$V_{DD} = 5$ V (see Note 1)	AGND	2.048	$V_{DD} - 1.5$	V
	$V_{DD} = 3$ V (see Note 1)	AGND	1.024	$V_{DD} - 1.5$	V
Load resistance, R_L		2			k Ω
Load capacitance, C_L				100	pF
Clock frequency, f_{CLK}				20	MHz
Operating free-air temperature, T_A	TLV5625C	0		70	°C
	TLV5625I	–40		85	

NOTE 1: Due to the x2 output buffer, a reference input voltage $\geq (V_{DD} - 0.4 \text{ V})/2$ causes clipping of the transfer function.



2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

electrical characteristics over recommended operating conditions (unless otherwise noted)

power supply

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I _{DD}	Power supply current	No load, All inputs = AGND or V _{DD} , DAC latch = 0x800	Fast		1.8	2.3	mA
			Slow		0.8	1	
	Power-down supply current				1	3	μA
PSRR	Power supply rejection ratio	Zero scale, See Note 2			–65		dB
		Full scale, See Note 3			–65		

NOTES: 2. Power supply rejection ratio at zero scale is measured by varying V_{DD} and is given by:

$$PSRR = 20 \log [(E_{ZS}(V_{DDmax}) - E_{ZS}(V_{DDmin})/V_{DDmax}]$$

3. Power supply rejection ratio at full scale is measured by varying V_{DD} and is given by:

$$PSRR = 20 \log [(E_G(V_{DDmax}) - E_G(V_{DDmin})/V_{DDmax}]$$

static DAC specifications

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
	Resolution			8			bits
INL	Integral nonlinearity	See Note 4			±0.3	±0.5	LSB
DNL	Differential nonlinearity	See Note 5			±0.07	±0.2	LSB
E _{ZS}	Zero-scale error (offset error at zero scale)	See Note 6				±12	mV
E _{ZS} TC	Zero-scale-error temperature coefficient	See Note 7			10		ppm/°C
E _G	Gain error	See Note 8				±0.5	% full scale V
E _G TC	Gain-error temperature coefficient	See Note 9			10		ppm/°C

NOTES: 4. The relative accuracy of integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale, excluding the effects of zero-code and full-scale errors.

5. The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1-LSB amplitude change of any two adjacent codes.

6. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.

7. Zero-scale error temperature coefficient is given by: $E_{ZS} TC = [E_{ZS}(T_{max}) - E_{ZS}(T_{min})]/2V_{ref} \times 10^6/(T_{max} - T_{min})$.

8. Gain error is the deviation from the ideal output (2V_{ref} – 1 LSB) with an output load of 10 kΩ.

9. Gain temperature coefficient is given by: $E_G TC = [E_G(T_{max}) - E_G(T_{min})]/2V_{ref} \times 10^6/(T_{max} - T_{min})$.

output specifications

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V _O	Output voltage range	R _L = 10 kΩ		0		V _{DD} –0.4	V
	Output load regulation accuracy	V _O = 4.096 V, 2.048 V R _L = 2 kΩ				±0.29	% FS

reference input

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V _I	Input voltage range			0		V _{DD} –1.5	V
R _I	Input resistance				10		MΩ
C _I	Input capacitance				5		pF
Reference input bandwidth	REF = 0.2 V _{pp} + 1.024 V dc	Fast			1.3		MHz
		Slow			525		kHz
Reference feedthrough	REF = 1 V _{pp} at 1 kHz + 1.024 V dc (see Note 10)				–80		dB

NOTE 10: Reference feedthrough is measured at the DAC output with an input code = 0x000.

TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

electrical characteristics over recommended operating conditions (unless otherwise noted)
(Continued)

digital inputs

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH} High-level digital input current	$V_I = V_{DD}$			1	μA
I_{IL} Low-level digital input current	$V_I = 0 V$	-1			μA
C_i Input capacitance			8		pF

analog output dynamic performance

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{s(FS)}$ Output settling time, full scale	$R_L = 10 k\Omega$, $C_L = 100 pF$, See Note 11		1	3	μs
	Fast				
$t_{s(CC)}$ Output settling time, code to code	$R_L = 10 k\Omega$, $C_L = 100 pF$, See Note 12		1	10	μs
	Fast				
SR Slew rate	$R_L = 10 k\Omega$, $C_L = 100 pF$, See Note 13		3		V/ μs
	Fast				
Glitch energy	$DIN = 0$ to 1 , $FCLK = 100 kHz$, $\overline{CS} = V_{DD}$		0.5		nV-s
	Slow				
SNR Signal-to-noise ratio	$f_s = 102 kSPS$, $f_{out} = 1 kHz$, $R_L = 10 k\Omega$, $C_L = 100 pF$	52	54		dB
SINAD Signal-to-noise + distortion		48	49		
THD Total harmonic distortion		-50	-48		
SFDR Spurious free dynamic range		48	50		

- NOTES: 11. Settling time is the time for the output signal to remain within ± 0.5 LSB of the final measured value for a digital input code change of 0x020 to 0xFDF and 0xFDF to 0x020 respectively. Not tested, assured by design.
12. Settling time is the time for the output signal to remain within ± 0.5 LSB of the final measured value for a digital input code change of one count. Not tested, assured by design.
13. Slew rate determines the time it takes for a change of the DAC output from 10% to 90% of full-scale voltage.



TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

digital input timing requirements

	MIN	NOM	MAX	UNIT
$t_{su}(\overline{CS}-CK)$ Setup time, \overline{CS} low before first negative SCLK edge	10			ns
$t_{su}(C16-CS)$ Setup time, 16 th negative SCLK edge before \overline{CS} rising edge	10			ns
t_{wH} SCLK pulse width high	25			ns
t_{wL} SCLK pulse width low	25			ns
$t_{su}(D)$ Setup time, data ready before SCLK falling edge	10			ns
$t_h(D)$ Hold time, data held valid after SCLK falling edge	10			ns

timing requirements

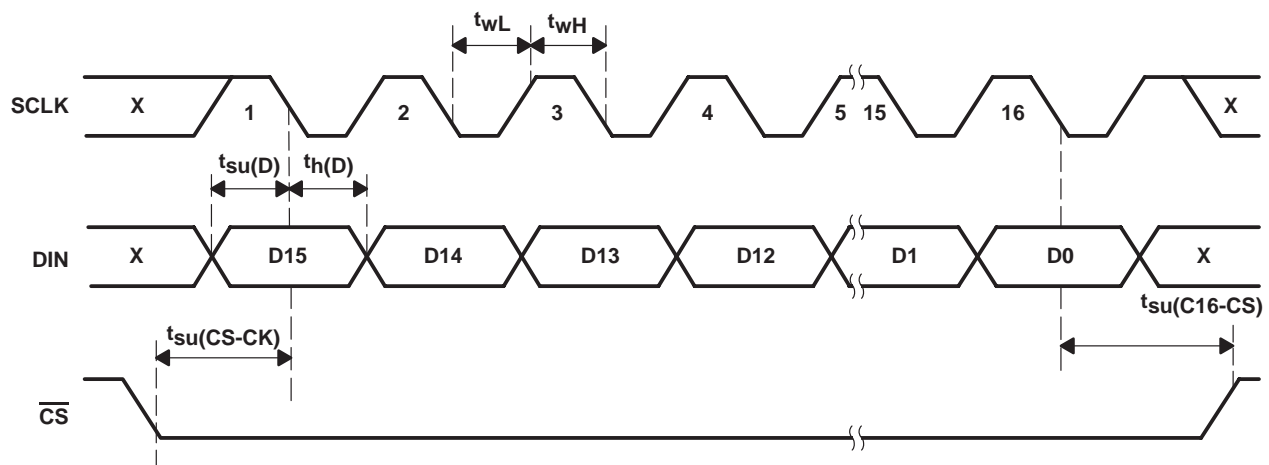


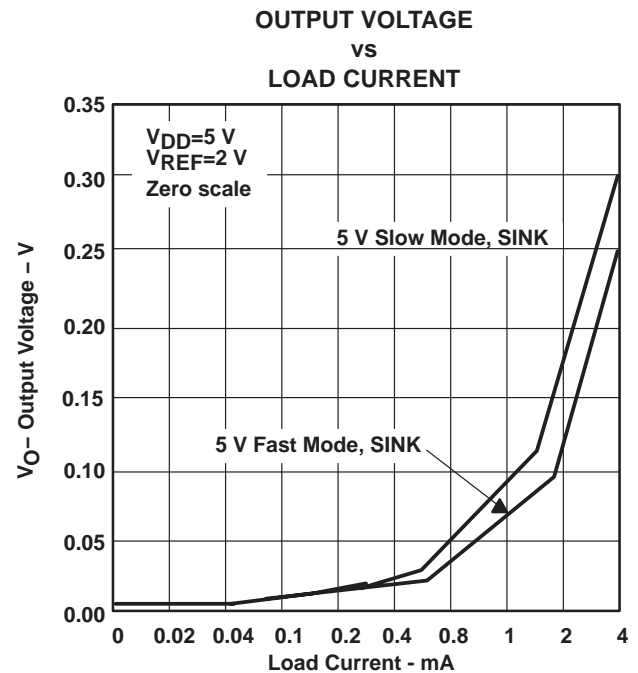
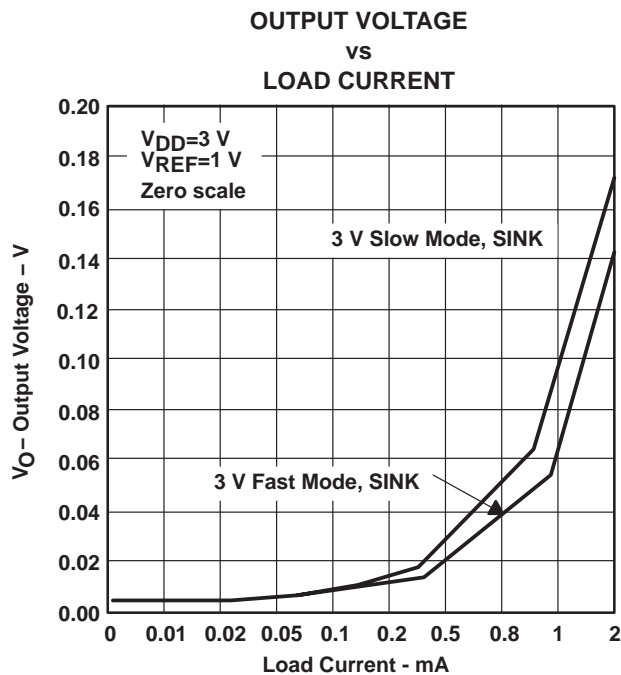
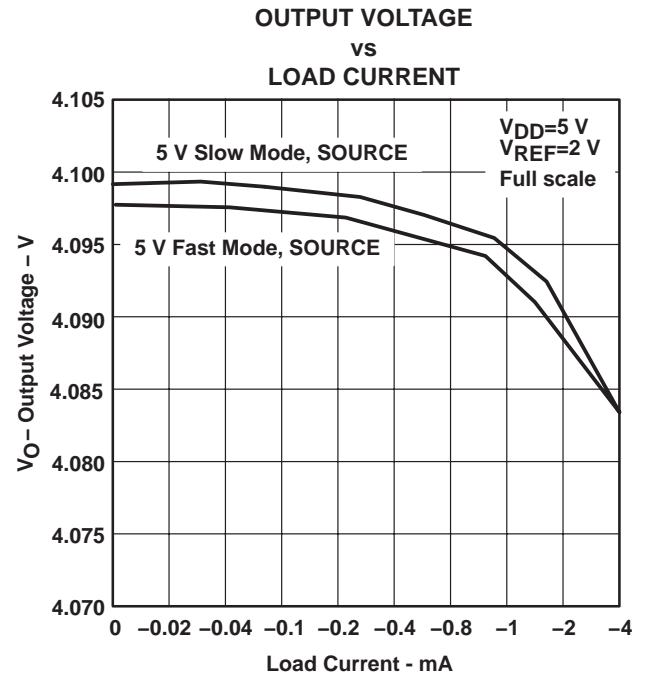
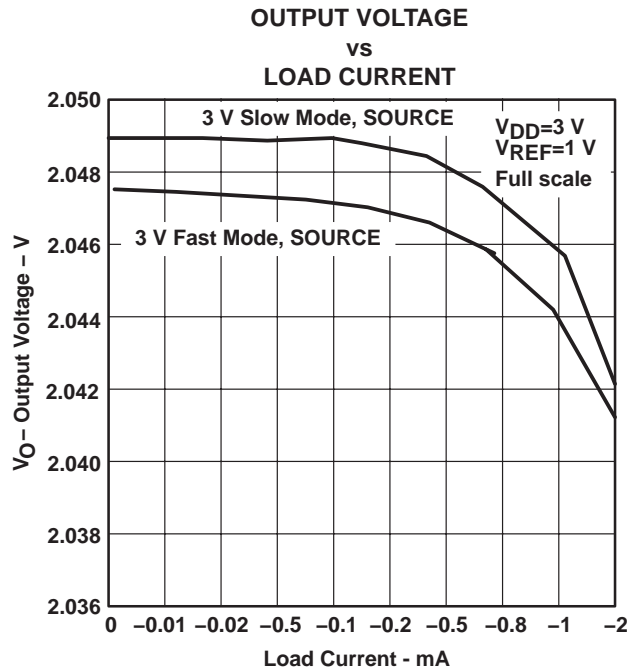
Figure 1. Timing Diagram

TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

TYPICAL CHARACTERISTICS



TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

TYPICAL CHARACTERISTICS

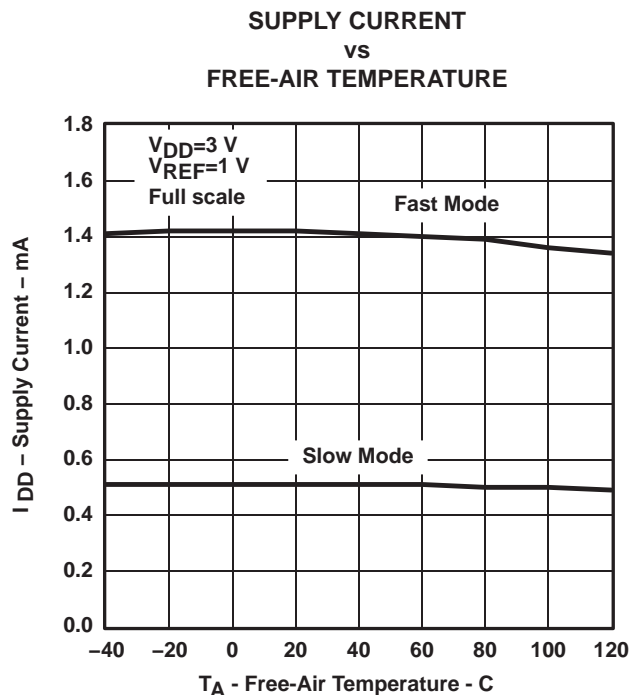


Figure 6

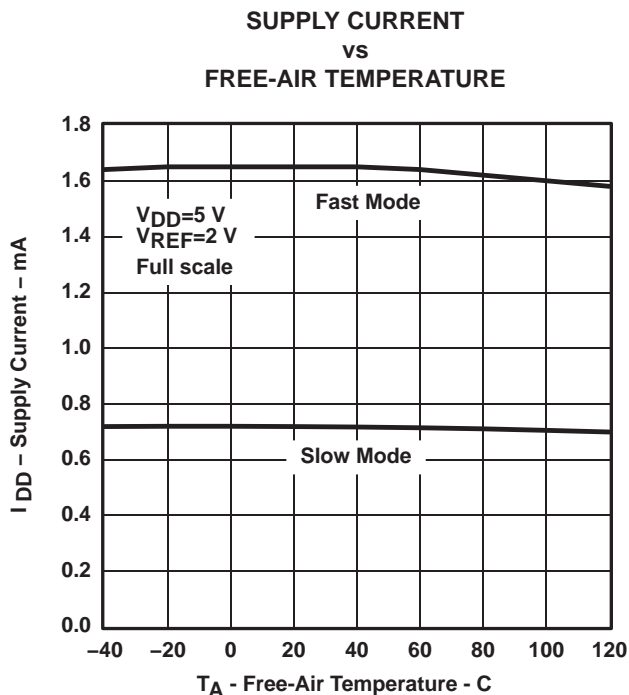


Figure 7

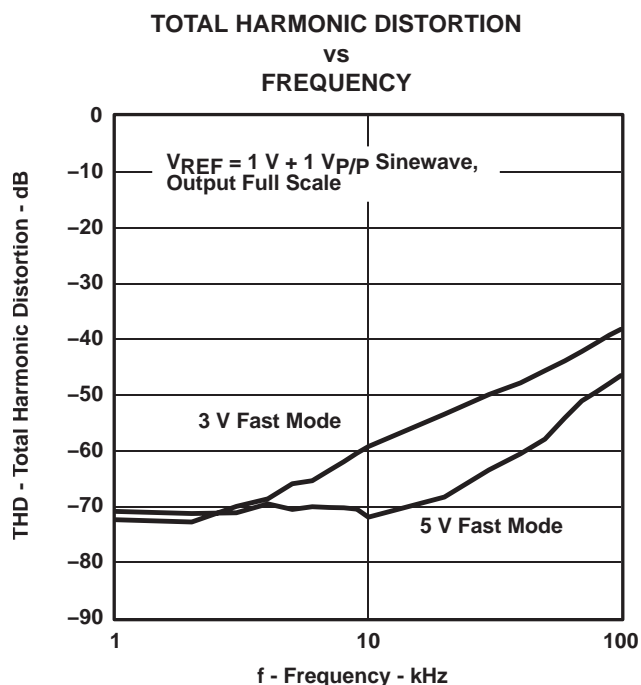


Figure 8

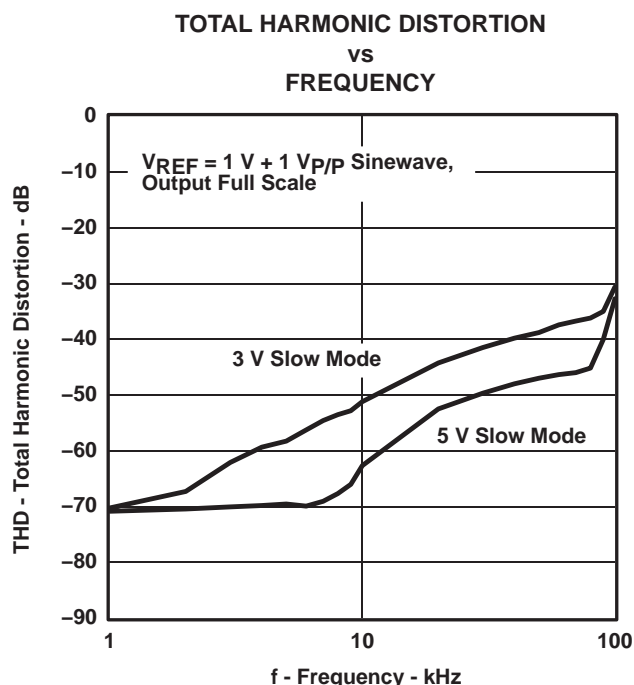


Figure 9

TYPICAL CHARACTERISTICS

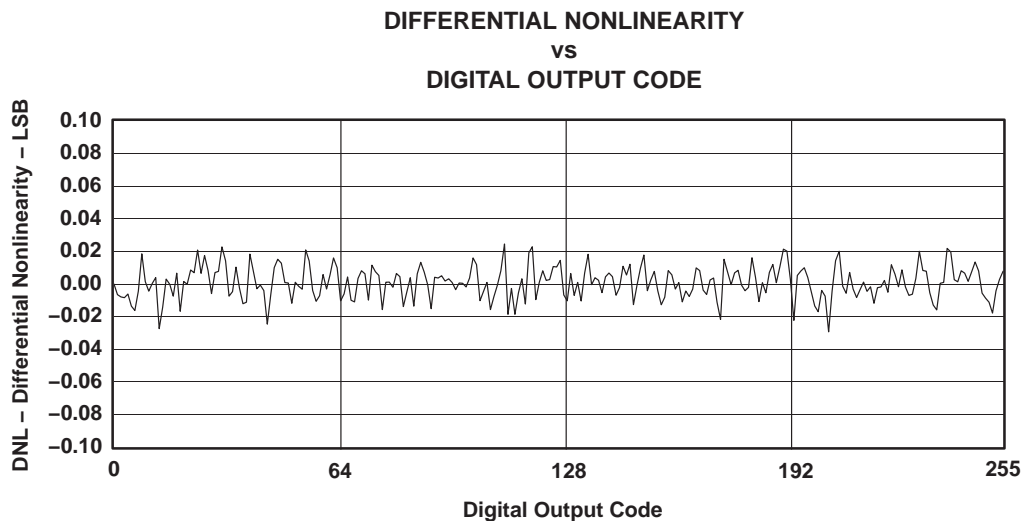


Figure 10

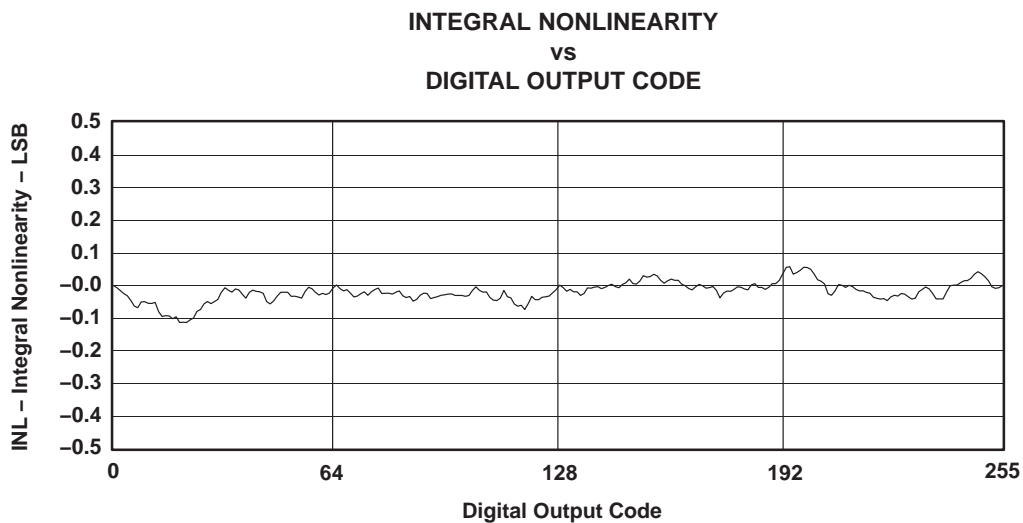


Figure 11

TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

APPLICATION INFORMATION

general function

The TLV5625 is a dual 8-bit, single-supply DAC, based on a resistor-string architecture. It consists of a serial interface, a speed and power-down control logic, a resistor string, and a rail-to-rail output buffer.

The output voltage (full scale determined by the reference) is given by:

$$2 \text{ REF } \frac{\text{CODE}}{2^n} \text{ [V]}$$

Where REF is the reference voltage and CODE is the digital input value within the range of 0_{10} to 2^n-1 , where $n=8$ (bits). The 16-bit data word, consisting of control bits and the new DAC value, is illustrated in the *data format* section. A power-on reset initially resets the internal latches to a defined state (all bits zero).

serial interface

A falling edge of $\overline{\text{CS}}$ starts shifting the data bit-per-bit (starting with the MSB) to the internal register on the falling edges of SCLK. After 16 bits have been transferred or $\overline{\text{CS}}$ rises, the content of the shift register is moved to the target latches (DAC A, DAC B, BUFFER, CONTROL), depending on the control bits within the data word.

Figure 2 shows examples of how to connect the TLV5625 to TMS320, SPI™, and Microwire™.

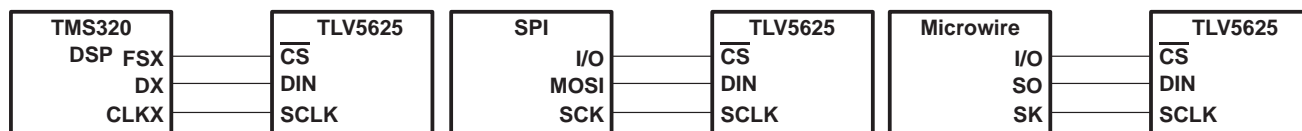


Figure 12. Three-Wire Interface

Notes on SPI™ and Microwire™: Before the controller starts the data transfer, the software has to generate a falling edge on the pin connected to $\overline{\text{CS}}$. If the word width is 8 bits (SPI™ and Microwire™) two write operations must be performed to program the TLV5625. After the write operation(s), the holding registers or the control register are updated automatically on the 16th positive clock edge.

serial clock frequency and update rate

The maximum serial clock frequency is given by:

$$f_{\text{sclkmax}} = \frac{1}{t_{\text{whmin}} + t_{\text{wlmin}}} = 20 \text{ MHz}$$

The maximum update rate is:

$$f_{\text{updatemax}} = \frac{1}{16 (t_{\text{whmin}} + t_{\text{wlmin}})} = 1.25 \text{ MHz}$$

Note that the maximum update rate is just a theoretical value for the serial interface, as the settling time of the TLV5625 should also be considered.

TLV5625

2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS233D – JULY 1999 – REVISED JULY 2002

APPLICATION INFORMATION

data format

The 16-bit data word for the TLV5625 consists of two parts:

- Program bits (D15..D12)
- New data (D11..D4)

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R1	SPD	PWR	R0	MSB 8 Data bits								LSB	0	0	0

SPD: Speed control bit 1 → fast mode 0 → slow mode
PWR: Power control bit 1 → power down 0 → normal operation
On power up, SPD and PWD are reset to 0 (slow mode and normal operation)

The following table lists all possible combination of register-select bits:

register-select bits

R1	R0	REGISTER
0	0	Write data to DAC B and BUFFER
0	1	Write data to BUFFER
1	0	Write data to DAC A and update DAC B with BUFFER content
1	1	Reserved

The meaning of the 12 data bits depends on the register. If one of the DAC registers or the BUFFER is selected, then the 12 data bits determine the new DAC value:

examples of operation

- Set DAC A output, select fast mode:

Write new DAC A value and update DAC A output:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
1	1	0	0	New DAC A output value								0	0	0	0

The DAC A output is updated on the rising clock edge after D0 is sampled.

- Set DAC B output, select fast mode:

Write new DAC B value to BUFFER and update DAC B output:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	1	0	0	New BUFFER content and DAC B output value								0	0	0	0

The DAC A output is updated on the rising clock edge after D0 is sampled.

- Set DAC A value, set DAC B value, update both simultaneously, select slow mode:

1. Write data for DAC B to BUFFER:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	1	New DAC B value								0	0	0	0

2. Write new DAC A value and update DAC A and B simultaneously:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
1	0	0	0	New DAC A value								0	0	0	0



APPLICATION INFORMATION

examples of operation (continued)

Both outputs are updated on the rising clock edge after D0 from the DAC A data word is sampled.

- Set power-down mode:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
X	X	1	X	X	X	X	X	X	X	X	X	X	X	X	X

X = Don't care

linearity, offset, and gain error using single ended supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset, the output voltage changes on the first code change. With a negative offset, the output voltage may not change with the first code, depending on the magnitude of the offset voltage.

The output amplifier attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground and clamps the output at 0 V.

The output voltage then remains at zero until the input code value produces a sufficient positive output voltage to overcome the negative offset voltage, resulting in the transfer function shown in Figure 13.

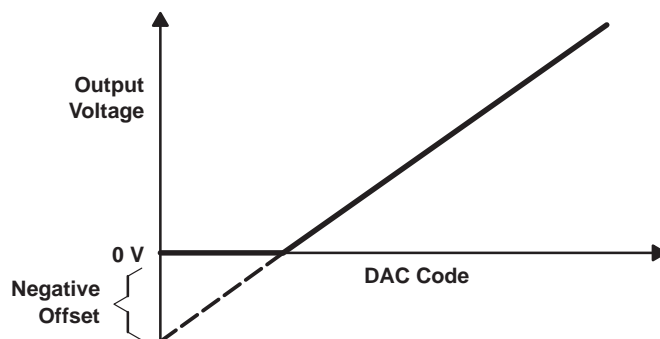


Figure 13. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces this breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below the ground rail.

For a DAC, linearity is measured between zero-input code (all inputs 0) and full-scale code (all inputs 1) after offset and full scale are adjusted out or accounted for in some way. However, single supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity is measured between full-scale code and the lowest code that produces a positive output voltage.

power-supply bypassing and ground management

Printed-circuit boards that use separate analog and digital ground planes offer the best system performance. Wire-wrap boards do not perform well and should not be used. The two ground planes should be connected together at the low-impedance power-supply source. The best ground connection may be achieved by connecting the DAC AGND terminal to the system analog ground plane, making sure that analog ground currents are well managed and there are negligible voltage drops across the ground plane.

A 0.1- μ F ceramic-capacitor bypass should be connected between V_{DD} and AGND and mounted with short leads as close as possible to the device. Use of ferrite beads may further isolate the system analog supply from the digital power supply.

Figure 14 shows the ground plane layout and bypassing technique.

APPLICATION INFORMATION

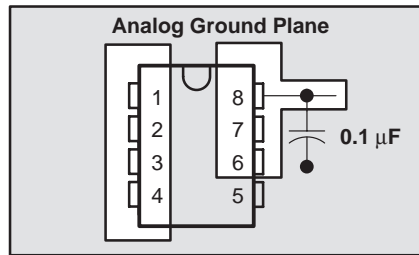


Figure 14. Power-Supply Bypassing

definitions of specifications and terminology

integral nonlinearity (INL)

The relative accuracy or integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.

differential nonlinearity (DNL)

The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.

zero-scale error (E_{zs})

Zero-scale error is defined as the deviation of the output from 0 V at a digital input value of 0.

gain error (E_G)

Gain error is the error in slope of the DAC transfer function.

signal-to-noise ratio + distortion (S/N+D)

S/N+D is the ratio of the rms value of the output signal to the rms sum of all other spectral components below the Nyquist frequency, including harmonics but excluding dc. The value for S/N+D is expressed in decibels.

spurious free dynamic range (SFDR)

SFDR is the difference between the rms value of the output signal and the rms value of the largest spurious signal within a specified bandwidth. The value for SFDR is expressed in decibels.

total harmonic distortion (THD)

THD is the ratio of the rms sum of the first six harmonic components to the rms value of the fundamental signal and is expressed in decibels.

TLV5625
2.7-V TO 5.5-V LOW-POWER DUAL 8-BIT DIGITAL-TO-ANALOG
CONVERTER WITH POWER DOWN

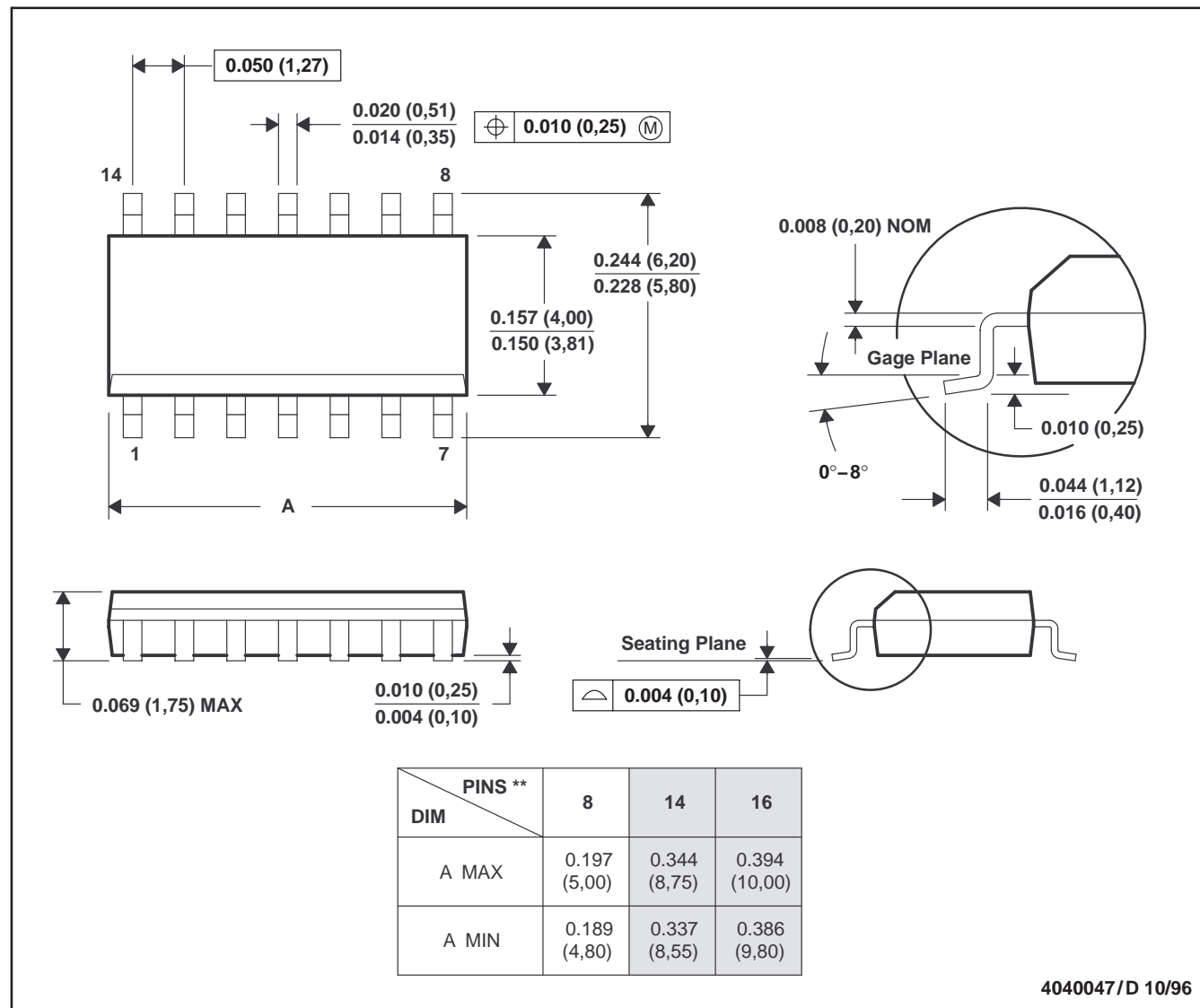
SLAS233D – JULY 1999 – REVISED JULY 2002

MECHANICAL DATA

D (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLV5625CD	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV5625
TLV5625CD.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV5625
TLV5625CDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV5625
TLV5625CDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV5625
TLV5625ID	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY5625
TLV5625ID.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY5625
TLV5625IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY5625
TLV5625IDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY5625

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV5625CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV5625IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV5625CDR	SOIC	D	8	2500	350.0	350.0	43.0
TLV5625IDR	SOIC	D	8	2500	350.0	350.0	43.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TLV5625CD	D	SOIC	8	75	505.46	6.76	3810	4
TLV5625CD.A	D	SOIC	8	75	505.46	6.76	3810	4
TLV5625ID	D	SOIC	8	75	505.46	6.76	3810	4
TLV5625ID.A	D	SOIC	8	75	505.46	6.76	3810	4

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated